

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT2946421

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
MOON CHUL LEE	07/09/2014
IN SANG SONG	07/09/2014
DUCK HWAN KIM	07/09/2014
CHUL SOO KIM	07/09/2014
SANG UK SON	07/09/2014
JEA SHIK SHIN	07/09/2014
HO SOO PARK	07/09/2014
JING CUI	07/14/2014
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Property Type	Number
Application Number:	14353561
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ATTORNEY DOCKET NUMBER:	012052.0825
NAME OF SUBMITTER:	S. MAHMOOD AHMAD
SIGNATURE:	/S.Mahmood Ahmad/
DATE SIGNED:	07/21/2014
Total Attachments: 6	

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ASSIGNMENT

For valuable consideration, we,

- Moon Chul LEE** c/o Samsung Advanced Institute of Technology
97, Samsung 2-ro, Giheung-gu, Yongin-si, Gyeonggi-do
446-712 Republic of Korea
- In Sang SONG** c/o Samsung Advanced Institute of Technology
97, Samsung 2-ro, Giheung-gu, Yongin-si, Gyeonggi-do
446-712 Republic of Korea
- Duck Hwan KIM** c/o Samsung Advanced Institute of Technology
97, Samsung 2-ro, Giheung-gu, Yongin-si, Gyeonggi-do
446-712 Republic of Korea
- Chul Soo KIM** c/o Samsung Advanced Institute of Technology
97, Samsung 2-ro, Giheung-gu, Yongin-si, Gyeonggi-do
446-712 Republic of Korea
- Sang Uk SON** c/o Samsung Advanced Institute of Technology
97, Samsung 2-ro, Giheung-gu, Yongin-si, Gyeonggi-do
446-712 Republic of Korea
- Jea Shik SHIN** c/o Samsung Advanced Institute of Technology
97, Samsung 2-ro, Giheung-gu, Yongin-si, Gyeonggi-do
446-712 Republic of Korea
- Ho Soo PARK** c/o Samsung Advanced Institute of Technology
97, Samsung 2-ro, Giheung-gu, Yongin-si, Gyeonggi-do
446-712 Republic of Korea
- Jing CUI** c/o Samsung Advanced Institute of Technology
97, Samsung 2-ro, Giheung-gu, Yongin-si, Gyeonggi-do
446-712 Republic of Korea

hereby assign to:

Samsung Electronics Co., Ltd.
129, Samsung-ro, Yeongtong-gu
Suwon-si, Gyeonggi-do 443-742
Republic of Korea

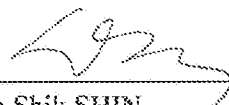
and its successors and assigns (collectively hereinafter called "the Assignee"), the entire right, title, and interest throughout the world in the inventions and improvements that are the subject of U.S. Patent Application Number 14/353,561 filed April 23, 2014 in the U.S. Patent & Trademark Office, signed by us and entitled:

**THIN FILM BULK ACOUSTIC RESONATOR AND METHOD FOR
MANUFACTURING SAME**

We authorize and request the attorneys appointed in said application to hereafter complete this Assignment by inserting above the application number and filing date of said application when known, and to correct any typographical errors that may be discovered in this

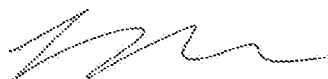
012052.0825

This 9 day of July, 2014



Jea Shik SHIN

This 9 day of July, 2014



Ho Soo PARK

This _____ day of _____, 2014

Jing CUI

ASSIGNMENT

For valuable consideration, we,

Moon Chul LEE	c/o Samsung Advanced Institute of Technology 97, Samsung 2-ro, Giheung-gu, Yongin-si, Gyeonggi-do 446-712 Republic of Korea
In Sang SONG	c/o Samsung Advanced Institute of Technology 97, Samsung 2-ro, Giheung-gu, Yongin-si, Gyeonggi-do 446-712 Republic of Korea
Duck Hwan KIM	c/o Samsung Advanced Institute of Technology 97, Samsung 2-ro, Giheung-gu, Yongin-si, Gyeonggi-do 446-712 Republic of Korea
Chul Soo KIM	c/o Samsung Advanced Institute of Technology 97, Samsung 2-ro, Giheung-gu, Yongin-si, Gyeonggi-do 446-712 Republic of Korea
Sang Uk SON	c/o Samsung Advanced Institute of Technology 97, Samsung 2-ro, Giheung-gu, Yongin-si, Gyeonggi-do 446-712 Republic of Korea
Jea Shik SHIN	c/o Samsung Advanced Institute of Technology 97, Samsung 2-ro, Giheung-gu, Yongin-si, Gyeonggi-do 446-712 Republic of Korea
Ho Soo PARK	c/o Samsung Advanced Institute of Technology 97, Samsung 2-ro, Giheung-gu, Yongin-si, Gyeonggi-do 446-712 Republic of Korea
Jing CUI	c/o Samsung Advanced Institute of Technology 97, Samsung 2-ro, Giheung-gu, Yongin-si, Gyeonggi-do 446-712 Republic of Korea

hereby assign to:

Samsung Electronics Co., Ltd.
129, Samsung-ro, Yeongtong-gu
Suwon-si, Gyeonggi-do 443-742
Republic of Korea

and its successors and assigns (collectively hereinafter called "the Assignee"), the entire right, title, and interest throughout the world in the inventions and improvements that are the subject of U.S. Patent Application Number 14/353,561 filed April 23, 2014 in the U.S. Patent & Trademark Office, signed by us and entitled:

**THIN FILM BULK ACOUSTIC RESONATOR AND METHOD FOR
MANUFACTURING SAME**

We authorize and request the attorneys appointed in said application to hereafter complete this Assignment by inserting above the application number and filing date of said application when known, and to correct any typographical errors that may be discovered in this

Assignment; this Assignment including said application, any and all United States and foreign patents, utility models, and design registrations granted for any of said inventions or improvements, and the right to claim priority based on the filing date of said application under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes; and we authorize the Assignee to apply in all countries in our name or in its own name for patents, utility models, design registrations, and like rights of exclusion, and for inventors' certificates for said inventions and improvements; and we agree for ourselves and our respective heirs, legal representatives, and assigns without further compensation to perform such lawful acts and to sign such further applications, Assignments, preliminary statements, and other lawful documents as the Assignee may reasonably request to effectuate fully this Assignment.

In TESTIMONY/WITNESS Whereof, we, the undersigned inventors (Assignors), intending to be legally bound, have hereto affixed our signatures.

This _____ day of _____, 2014

Moon Chul LEE

This _____ day of _____, 2014

In Sang SONG

This _____ day of _____, 2014

Duck Hwan KIM

This _____ day of _____, 2014

Chul Soo KIM

This _____ day of _____, 2014

Sang Uk SON

012052.0825

This _____ day of _____, 2014

Jea Shik SHIN

This _____ day of _____, 2014

Ho Soo PARK

This 14 day of July, 2014



Jing CUI